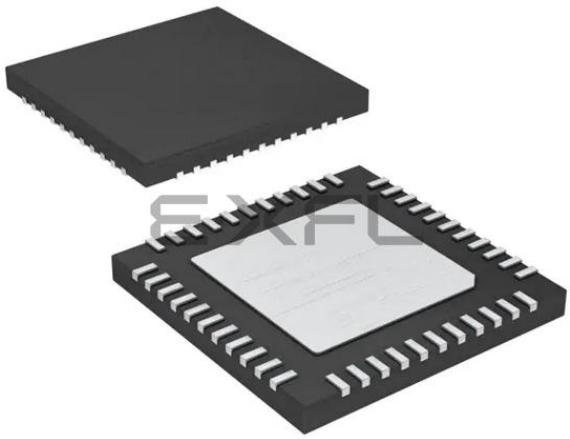

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf45k22-e-ml

2.4 Clock Source Modes

Clock Source modes can be classified as external or internal.

- External Clock modes rely on external circuitry for the clock source. Examples are: Clock modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC mode) circuits.
- Internal clock sources are contained internally within the Oscillator block. The Oscillator block has three internal oscillators: the 16 MHz High-Frequency Internal Oscillator (HFINTOSC), 500 kHz Medium-Frequency Internal Oscillator (MFINTOSC) and the 31.25 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS<1:0>) bits of the OSCCON register. See **Section 2.11 "Clock Switching"** for additional information.

2.5 External Clock Modes

2.5.1 OSCILLATOR START-UP TIMER (OST)

When the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module. When switching between clock sources, a delay is required to allow the new clock to stabilize. These oscillator delays are shown in Table 2-2.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 2.12 "Two-Speed Clock Start-up Mode"**).

TABLE 2-2: OSCILLATOR DELAY EXAMPLES

Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR/BOR	LFINTOSC MFINTOSC HFINTOSC	31.25 kHz 31.25 kHz to 500 kHz 31.25 kHz to 16 MHz	Oscillator Start-up Delay (TIOSC_ST)
Sleep/POR/BOR	EC, RC	DC – 64 MHz	2 instruction cycles
LFINTOSC (31.25 kHz)	EC, RC	DC – 64 MHz	1 cycle of each
Sleep/POR/BOR	LP, XT, HS	32 kHz to 40 MHz	1024 Clock Cycles (OST)
Sleep/POR/BOR	4xPLL	32 MHz to 64 MHz	1024 Clock Cycles (OST) + 2 ms
LFINTOSC (31.25 kHz)	LFINTOSC HFINTOSC	31.25 kHz to 16 MHz	1 μs (approx.)

2.5.2 EC MODE

The External Clock (EC) mode allows an externally generated logic level as the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input and the OSC2 is available for general purpose I/O. Figure 2-5 shows the pin connections for EC mode.

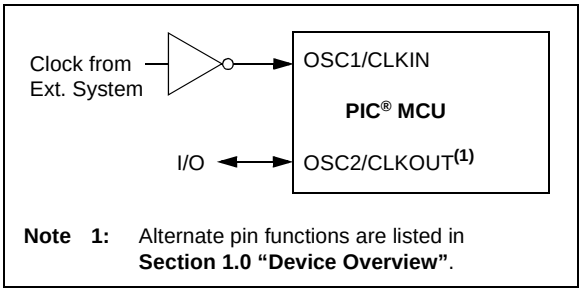
The External Clock (EC) offers different power modes, Low Power (ECLP), Medium Power (ECMP) and High Power (ECHP), selectable by the FOSC<3:0> bits. Each mode is best suited for a certain range of frequencies. The ranges are:

- ECLP – below 500 kHz
- ECMP – between 500 kHz and 16 MHz
- ECHP – above 16 MHz

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep.

Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 2-5: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Alternate pin functions are listed in **Section 1.0 "Device Overview"**.

TABLE 5-2: REGISTER FILE SUMMARY FOR PIC18(L)F2X/4XK22 DEVICES (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR
FD1h	WDTCON	—	—	—	—	—	—	—	SWDTEN	---- ---0
FD0h	RCON	IPEN	SBOREN	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	01-1 1100
FCFh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx
FCEh	TMR1L	Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx
FCDh	T1CON	TMR1CS<1:0>		T1CKPS<1:0>		T1SOSCEN	$\overline{T1SYNC}$	T1RD16	TMR1ON	0000 0000
FCCh	T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{DONE}$	T1GVAL	T1GSS<1:0>		0000 xx00
FCBh	SSP1CON3	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	0000 0000
FCAh	SSP1MSK	SSP1 MASK Register bits								1111 1111
FC9h	SSP1BUF	SSP1 Receive Buffer/Transmit Register								xxxx xxxx
FC8h	SSP1ADD	SSP1 Address Register in I^2C Slave Mode. SSP1 Baud Rate Reload Register in I^2C Master Mode								0000 0000
FC7h	SSP1STAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	0000 0000
FC6h	SSP1CON1	WCOL	SSPOV	SSPEN	CKP	SSPM<3:0>				0000 0000
FC5h	SSP1CON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000
FC4h	ADRESH	A/D Result, High Byte								xxxx xxxx
FC3h	ADRESL	A/D Result, Low Byte								xxxx xxxx
FC2h	ADCON0	—	CHS<4:0>					GO/$\overline{DONE}$	ADON	--00 0000
FC1h	ADCON1	TRIGSEL	—	—	—	PVCFG<1:0>		NVCFG<1:0>		0--- 0000
FC0h	ADCON2	ADFM	—	ACQT<2:0>			ADCS<2:0>			0-00 0000
FBFh	CCPR1H	Capture/Compare/PWM Register 1, High Byte								xxxx xxxx
FBEh	CCPR1L	Capture/Compare/PWM Register 1, Low Byte								xxxx xxxx
FBDh	CCP1CON	P1M<1:0>		DC1B<1:0>		CCP1M<3:0>				0000 0000
FBCh	TMR2	Timer2 Register								0000 0000
FBBh	PR2	Timer2 Period Register								1111 1111
FBAh	T2CON	—	T2OUTPS<3:0>				TMR2ON	T2CKPS<1:0>		-000 0000
FB9h	PSTR1CON	—	—	—	STR1SYNC	STR1D	STR1C	STR1B	STR1A	---0 0001
FB8h	BAUDCON1	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	—	WUE	ABDEN	0100 0-00
FB7h	PWM1CON	P1RSEN	P1DC<6:0>							0000 0000
FB6h	ECCP1AS	CCP1ASE	CCP1AS<2:0>			PSS1AC<1:0>		PSS1BD<1:0>		0000 0000
FB4h	T3GCON	TMR3GE	T3GPOL	T3GTM	T3GSPM	T3GGO/$\overline{DONE}$	T3GVAL	T3GSS<1:0>		0000 0x00
FB3h	TMR3H	Holding Register for the Most Significant Byte of the 16-bit TMR3 Register								xxxx xxxx
FB2h	TMR3L	Least Significant Byte of the 16-bit TMR3 Register								xxxx xxxx
FB1h	T3CON	TMR3CS<1:0>		T3CKPS<1:0>		T3SOSCEN	$\overline{T3SYNC}$	T3RD16	TMR3ON	0000 0000
FB0h	SPBRGH1	EUSART1 Baud Rate Generator, High Byte								0000 0000
FAFh	SPBRG1	EUSART1 Baud Rate Generator, Low Byte								0000 0000
FAEh	RCREG1	EUSART1 Receive Register								0000 0000
FADh	TXREG1	EUSART1 Transmit Register								0000 0000
FACh	TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010
FABh	RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x
FAAh	EEADRH(5)	—	—	—	—	—	—	EEADR<9:8>		---- --00
FA9h	EEADR	EEADR<7:0>								0000 0000
FA8h	EEDATA	EEPROM Data Register								0000 0000
FA7h	EECON2	EEPROM Control Register 2 (not a physical register)								---- --00
FA6h	EECON1	EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD	xx-0 x000
FA5h	IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	CTMUIP	TMR5GIP	TMR3GIP	TMR1GIP	0000 0000
FA4h	PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	CTMUIF	TMR5GIF	TMR3GIF	TMR1GIF	0000 0000
FA3h	PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	CTMUIE	TMR5GIE	TMR3GIE	TMR1GIE	0000 0000

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition

Note 1: PIC18(L)F4XK22 devices only.
2: PIC18(L)F2XK22 devices only.
3: PIC18(L)F23/24K22 and PIC18(L)F43/44K22 devices only.
4: PIC18(L)F26K22 and PIC18(L)F46K22 devices only.

5.4.5 STATUS REGISTER

The STATUS register, shown in Register 5-2, contains the arithmetic status of the ALU. As with any other SFR, it can be the operand for any instruction.

If the STATUS register is the destination for an instruction that affects the Z, DC, C, OV or N bits, the results of the instruction are not written; instead, the STATUS register is updated according to the instruction performed. Therefore, the result of an instruction with the STATUS register as its destination may be different than intended. As an example, CLRF STATUS will set the Z bit and leave the remaining Status bits unchanged ('000u u1uu').

It is recommended that only BCF, BSF, SWAPF, MOVFF and MOVWF instructions are used to alter the STATUS register, because these instructions do not affect the Z, C, DC, OV or N bits in the STATUS register.

For other instructions that do not affect Status bits, see the instruction set summaries in **Section 25.2 "Extended Instruction Set"** and Table 25-3.

Note:	The C and DC bits operate as the $\overline{\text{borrow}}$ and digit $\overline{\text{borrow}}$ bits, respectively, in subtraction.

5.5 Register Definitions: Status

REGISTER 5-2: STATUS: STATUS REGISTER

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	N	OV	Z	DC(1)	C(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **N:** Negative bit
This bit is used for signed arithmetic (two's complement). It indicates whether the result was negative (ALU MSB = 1).
1 = Result was negative
0 = Result was positive

bit 3 **OV:** Overflow bit
This bit is used for signed arithmetic (two's complement). It indicates an overflow of the 7-bit magnitude which causes the sign bit (bit 7 of the result) to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 2 **Z:** Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{\text{Borrow}}$ bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)(1)
1 = A carry-out from the 4th low-order bit of the result occurred
0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{\text{Borrow}}$ bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)(1)
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{\text{Borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

REGISTER 7-1: EECON1: DATA EEPROM CONTROL 1 REGISTER

R/W-x	R/W-x	U-0	R/W-0	R/W-x	R/W-0	R/S-0	R/S-0
EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit		
S = Bit can be set by software, but not cleared		U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **EEPGD:** Flash Program or Data EEPROM Memory Select bit
- 1 = Access Flash program memory
- 0 = Access data EEPROM memory

bit 6 **CFGS:** Flash Program/Data EEPROM or Configuration Select bit
- 1 = Access Configuration registers
- 0 = Access Flash program or data EEPROM memory

bit 5 **Unimplemented:** Read as '0'

bit 4 **FREE:** Flash Row (Block) Erase Enable bit
- 1 = Erase the program memory block addressed by TBLPTR on the next WR command (cleared by completion of erase operation)
- 0 = Perform write-only

bit 3 **WRERR:** Flash Program/Data EEPROM Error Flag bit(1)
- 1 = A write operation is prematurely terminated (any Reset during self-timed programming in normal operation, or an improper write attempt)
- 0 = The write operation completed

bit 2 **WREN:** Flash Program/Data EEPROM Write Enable bit
- 1 = Allows write cycles to Flash program/data EEPROM
- 0 = Inhibits write cycles to Flash program/data EEPROM

bit 1 **WR:** Write Control bit
- 1 = Initiates a data EEPROM erase/write cycle or a program memory erase cycle or write cycle. (The operation is self-timed and the bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) by software.)
- 0 = Write cycle to the EEPROM is complete

bit 0 **RD:** Read Control bit
- 1 = Initiates an EEPROM read (Read takes one cycle. RD is cleared by hardware. The RD bit can only be set (not cleared) by software. RD bit cannot be set when EEPGD = 1 or CFGS = 1.)
- 0 = Does not initiate an EEPROM read

Note 1: When a WRERR occurs, the EEPGD and CFGS bits are not cleared. This allows tracing of the error condition.

TABLE 16-4: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page
BAUDCON1	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	—	WUE	ABDEN	271
BAUDCON2	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	—	WUE	ABDEN	271
PMD0	UART2MD	UART1MD	TMR6MD	TMR5MD	TMR4MD	TMR3MD	TMR2MD	TMR1MD	52
RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	270
RCSTA2	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	270
SPBRG1	EUSART1 Baud Rate Generator, Low Byte								—
SPBRGH1	EUSART1 Baud Rate Generator, High Byte								—
SPBRG2	EUSART2 Baud Rate Generator, Low Byte								—
SPBRGH2	EUSART2 Baud Rate Generator, High Byte								—
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	112
PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	CTMUIF	TMR5GIF	TMR3GIF	TMR1GIF	114
TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	269
TXSTA2	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	269

Legend: — = unimplemented, read as '0'. Shaded bits are not used by the BRG.

TABLE 16-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 64.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRxG value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	1200	0.00	239	1202	0.16	207	1200	0.00	143
2400	—	—	—	2400	0.00	119	2404	0.16	103	2400	0.00	71
9600	9615	0.16	103	9600	0.00	29	9615	0.16	25	9600	0.00	17
10417	10417	0.00	95	10286	-1.26	27	10417	0.00	23	10165	-2.42	16
19.2k	19.23k	0.16	51	19.20k	0.00	14	19.23k	0.16	12	19.20k	0.00	8
57.6k	58.82k	2.12	16	57.60k	0.00	7	—	—	—	57.60k	0.00	2
115.2k	111.11k	-3.55	8	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)	Actual Rate	% Error	SPBRGx value (decimal)
300	—	—	—	300	0.16	207	300	0.00	191	300	0.16	51
1200	1202	0.16	103	1202	0.16	51	1200	0.00	47	1202	0.16	12
2400	2404	0.16	51	2404	0.16	25	2400	0.00	23	—	—	—
9600	9615	0.16	12	—	—	—	9600	0.00	5	—	—	—
10417	10417	0.00	11	10417	0.00	5	—	—	—	—	—	—
19.2k	—	—	—	—	—	—	19.20k	0.00	2	—	—	—
57.6k	—	—	—	—	—	—	57.60k	0.00	0	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

24.5.2 DATA EEPROM CODE PROTECTION

The entire data EEPROM is protected from external reads and writes by two bits: CPD and WRTD. CPD inhibits external reads and writes of data EEPROM.

25.1.1 STANDARD INSTRUCTION SET

ADDLW **ADD literal to W**

Syntax: ADDLW k

Operands: $0 \le k \le 255$

Operation: $(W) + k \rightarrow W$

Status Affected: N, OV, C, DC, Z

Encoding:

0000	1111	kkkk	kkkk

Description: The contents of W are added to the 8-bit literal 'k' and the result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example: ADDLW 15h

Before Instruction
W = 10h
After Instruction
W = 25h

ADDWF **ADD W to f**

Syntax: ADDWF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $(W) + (f) \rightarrow$ dest

Status Affected: N, OV, C, DC, Z

Encoding:

0010	01da	ffff	ffff

Description: Add W to register 'f'. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: ADDWF REG, 0, 0

Before Instruction
W = 17h
REG = 0C2h
After Instruction
W = 0D9h
REG = 0C2h

Note: All PIC18 instructions may take an optional label argument preceding the instruction mnemonic for use in symbolic addressing. If a label is used, the instruction format then becomes: {label} instruction argument(s).

BZ **Branch if Zero**

Syntax: BZ n

Operands: -128 ≤ n ≤ 127

Operation: if ZERO bit is '1'
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0000	nnnn	nnnn

Description: If the ZERO bit is '1', then the program will branch.
The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: HERE BZ Jump

Before Instruction
PC = address (HERE)
After Instruction
If ZERO = 1;
PC = address (Jump)
If ZERO = 0;
PC = address (HERE + 2)

CALL **Subroutine Call**

Syntax: CALL k {,s}

Operands: 0 ≤ k ≤ 1048575
s ∈ [0,1]

Operation: (PC) + 4 → TOS,
k → PC<20:1>,
if s = 1
(W) → WS,
(Status) → STATUSS,
(BSR) → BSRS

Status Affected: None

Encoding:

1st word (k<7:0>)	1110	110s	$k_7$kkk	kkkk$_0$
2nd word(k<19:8>)	1111	k_{19}kkk	kkkk	kkkk$_8$

Description: Subroutine call of entire 2-Mbyte memory range. First, return address (PC + 4) is pushed onto the return stack. If 's' = 1, the W, STATUS and BSR registers are also pushed into their respective shadow registers, WS, STATUSS and BSRS. If 's' = 0, no update occurs (default). Then, the 20-bit value 'k' is loaded into PC<20:1>. CALL is a 2-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	PUSH PC to stack	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: HERE CALL THERE, 1

Before Instruction
PC = address (HERE)
After Instruction
PC = address (THERE)
TOS = address (HERE + 4)
WS = W
BSRS = BSR
STATUSS = Status

INCFSZ **Increment f, skip if 0**

Syntax: INCFSZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest,
skip if result = 0

Status Affected: None

Encoding:

0011	11da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If the result is '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    INCFSZ  CNT, 1, 0
NZERO   :
ZERO    :
```
Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT + 1
If CNT = 0;
PC = Address (ZERO)
If CNT ≠ 0;
PC = Address (NZERO)

INFSNZ **Increment f, skip if not 0**

Syntax: INFSNZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest,
skip if result ≠ 0

Status Affected: None

Encoding:

0100	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If the result is not '0', the next instruction, which is already fetched, is discarded and a NOP is executed instead, making it a 2-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    INFSNZ  REG, 1, 0
ZERO
NZERO
```
Before Instruction
PC = Address (HERE)
After Instruction
REG = REG + 1
If REG ≠ 0;
PC = Address (NZERO)
If REG = 0;
PC = Address (ZERO)

27.8 DC Characteristics: Input/Output Characteristics, PIC18(L)F2X/4XK22 (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D159	VOL	**Output Low Voltage** I/O ports	—	—	0.6	V	IOL = 8 mA, VDD = 5V IOL = 6 mA, VDD = 3.3V IOL = 1.8 mA, VDD = 1.8V
D161	VOH	**Output High Voltage(3)** I/O ports	VDD - 0.7	—	—	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 1 mA, VDD = 1.8V

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC® device be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

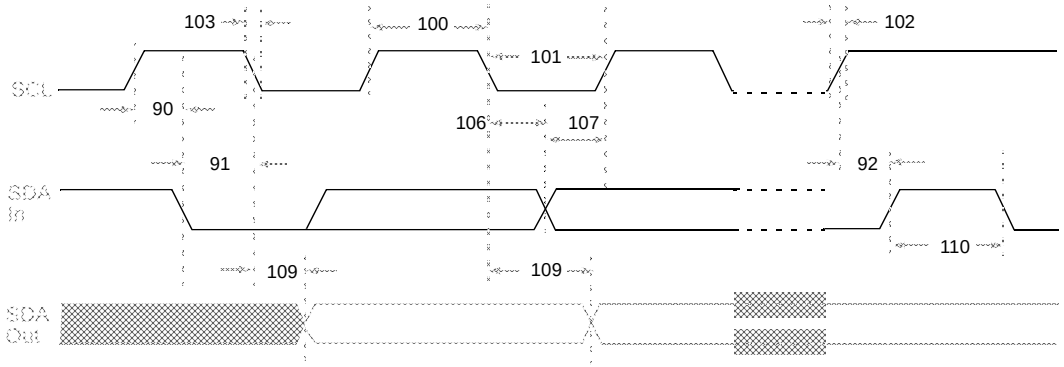
3: Negative current is defined as current sourced by the pin.

4: Parameter is characterized but not tested.

TABLE 27-15: I²C BUS START/STOP BITS REQUIREMENTS (SLAVE MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—		
91	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—		
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4700	—	ns	
			400 kHz mode	600	—		
93	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	
			400 kHz mode	600	—		

FIGURE 27-18: I²C BUS DATA TIMING



Note: Refer to Figure 27-6 for load conditions.

FIGURE 28-34: PIC18LF2X/4XK22 TYPICAL IDD: RC_IDLE LF-INTOSC 31 kHz

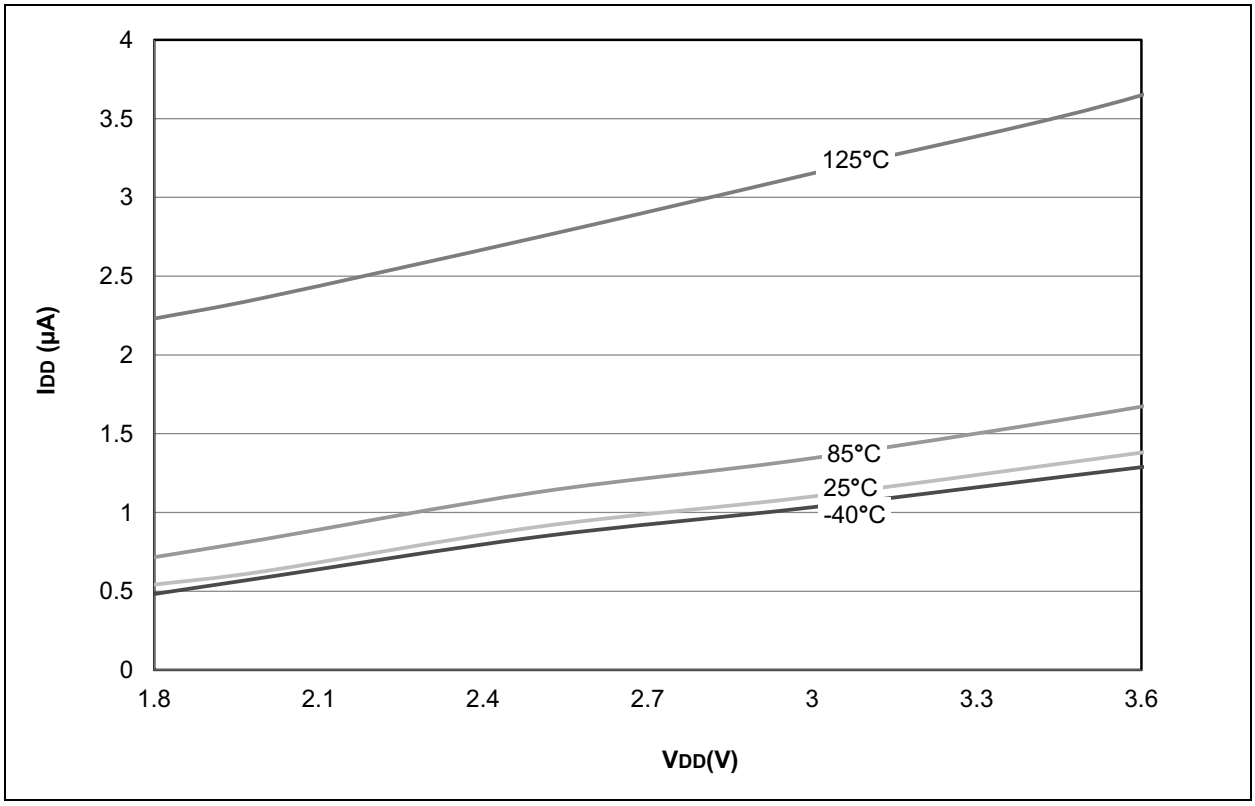


FIGURE 28-35: PIC18LF2X/4XK22 MAXIMUM IDD: RC_IDLE LF-INTOSC 31 kHz

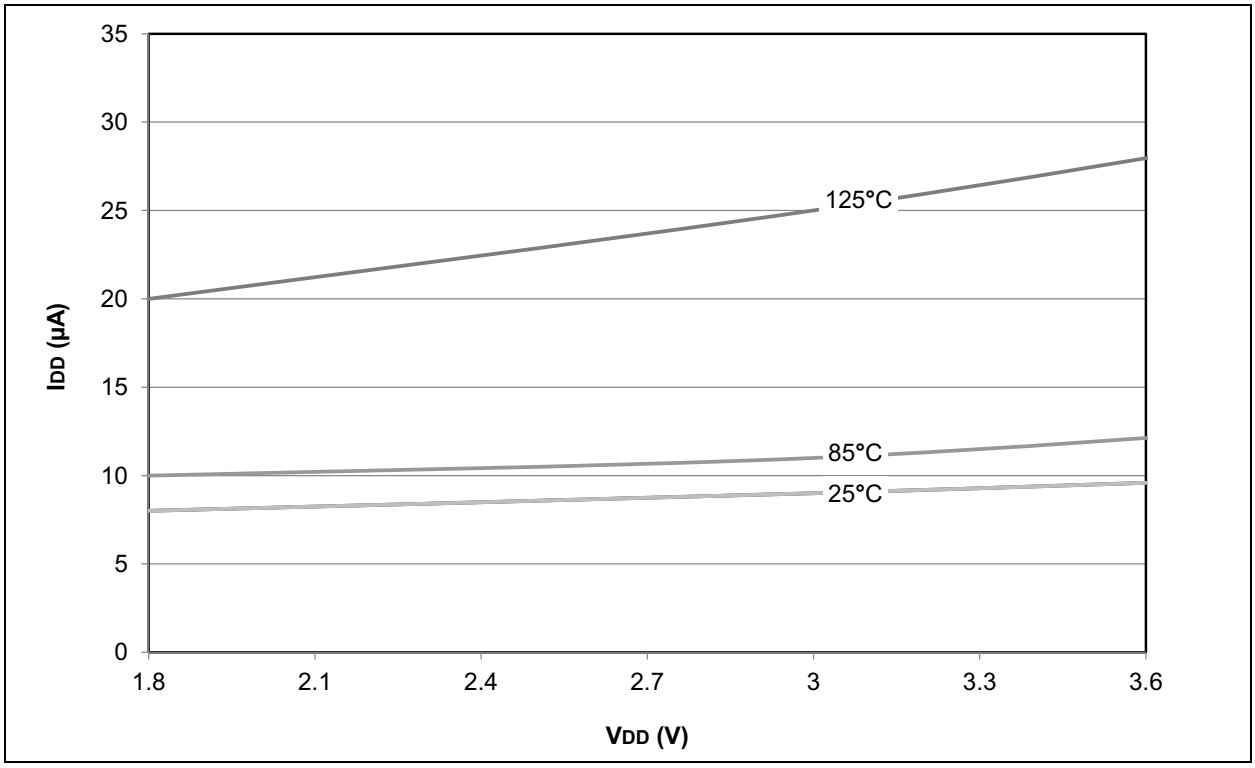


FIGURE 28-40: PIC18LF2X/4XK22 TYPICAL IDD: RC_IDLE HF-INTOSC

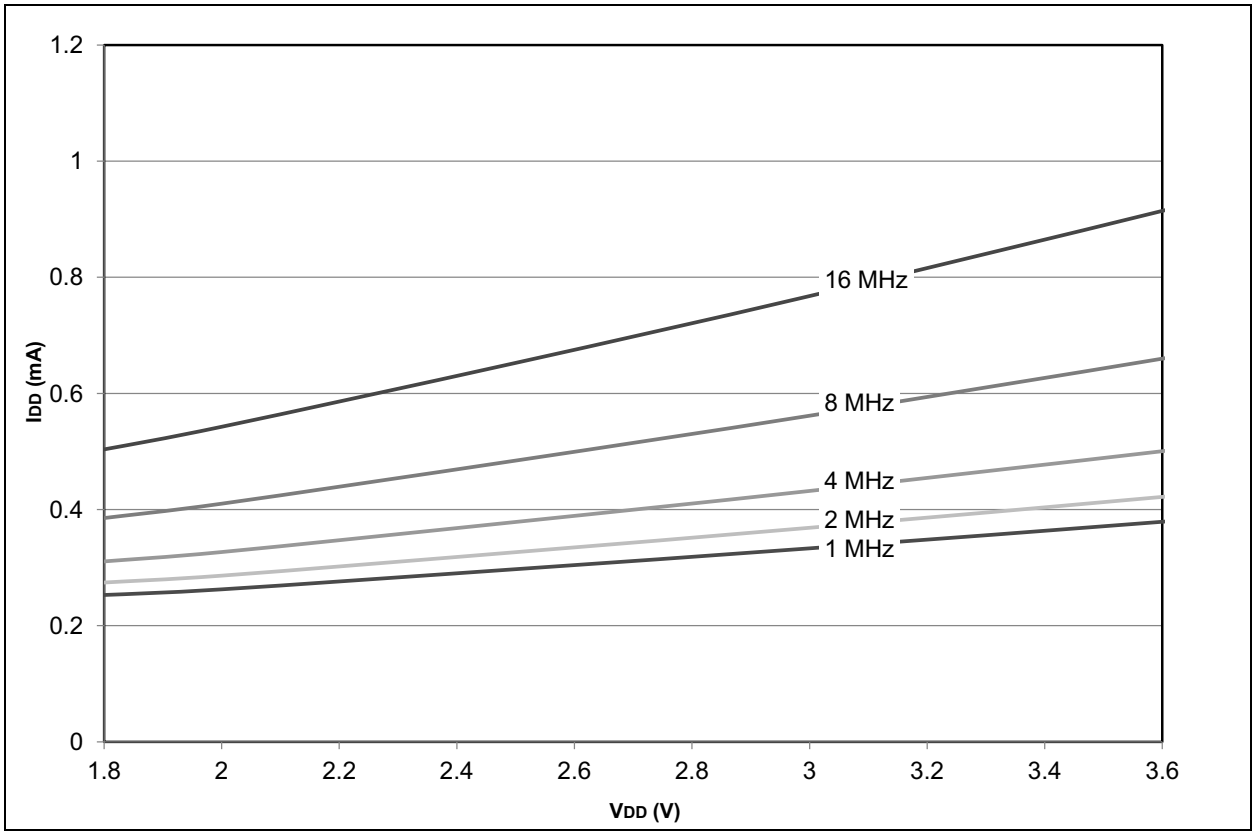


FIGURE 28-41: PIC18LF2X/4XK22 MAXIMUM IDD: RC_IDLE HF-INTOSC

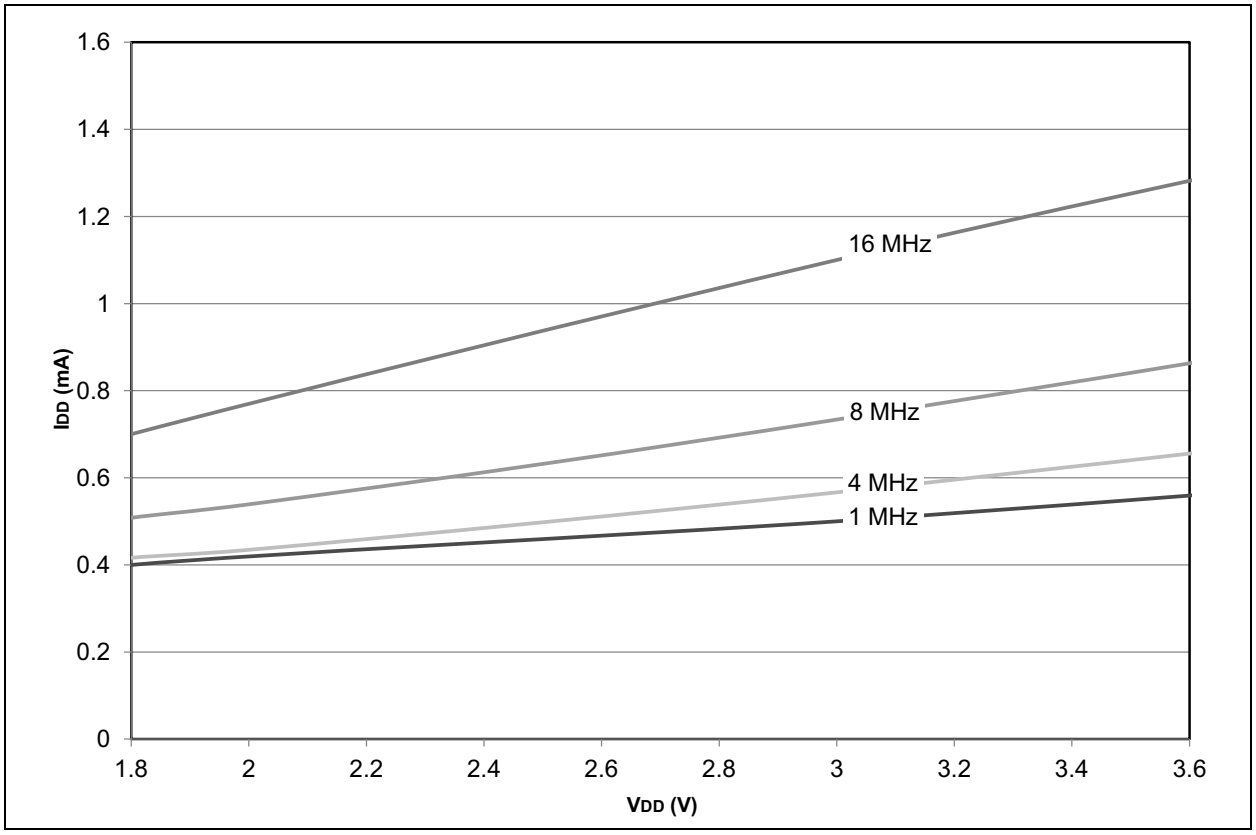
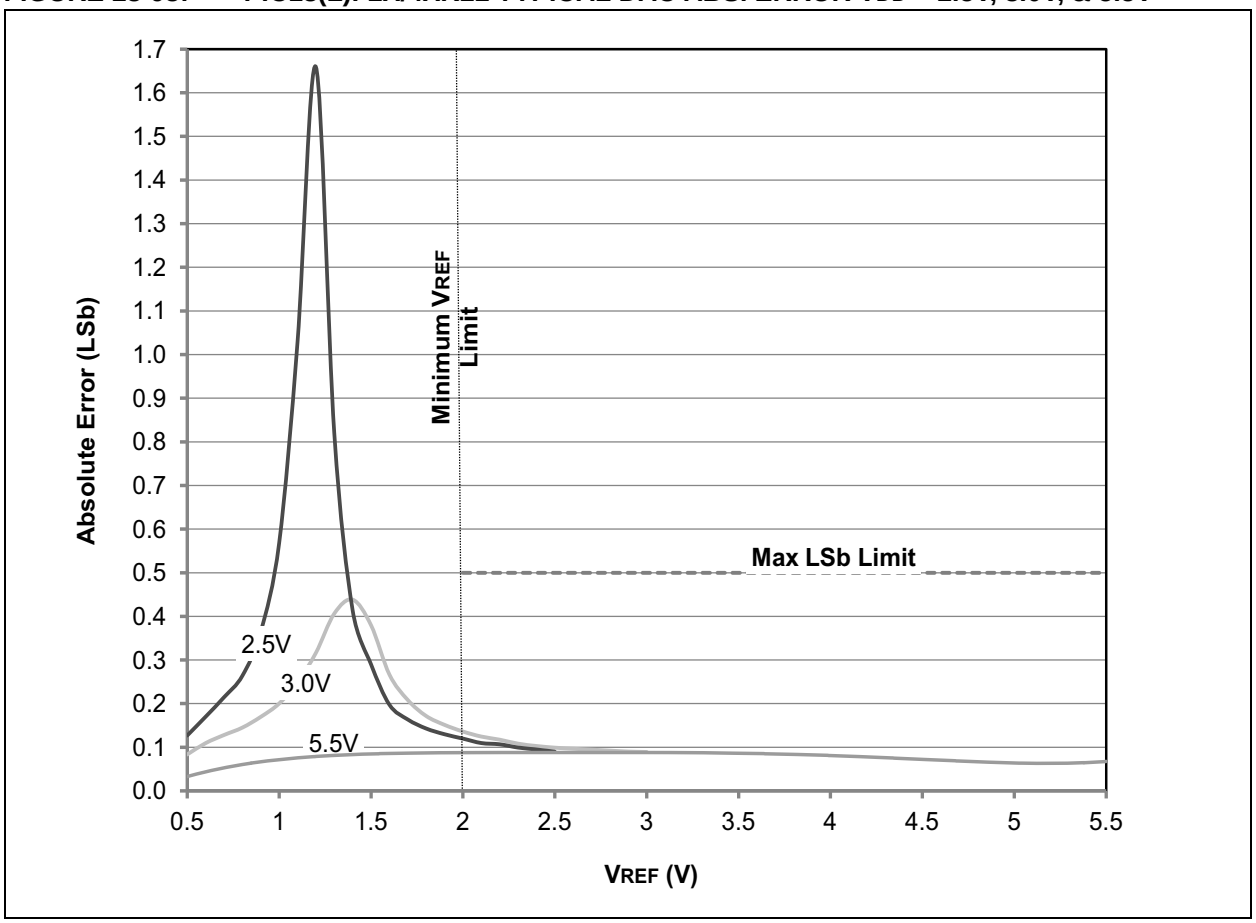
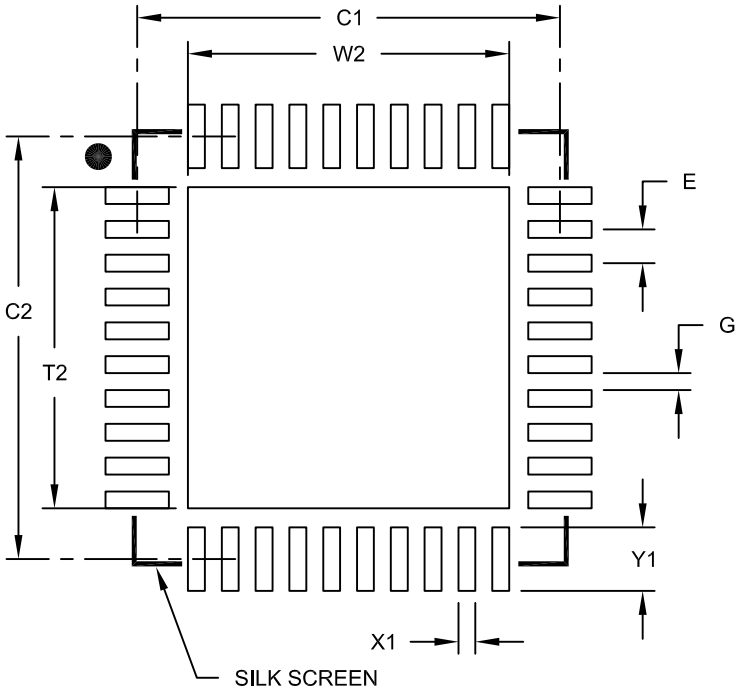


FIGURE 28-93: PIC18(L)F2X/4XK22 TYPICAL DAC ABS. ERROR V_{DD} = 2.5V, 3.0V, & 5.5V



40-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) - 5x5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			3.80
Optional Center Pad Length	T2			3.80
Contact Pad Spacing	C1		5.00	
Contact Pad Spacing	C2		5.00	
Contact Pad Width (X40)	X1			0.20
Contact Pad Length (X40)	Y1			0.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2156B

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ISBN: 978-1-5224-0907-6